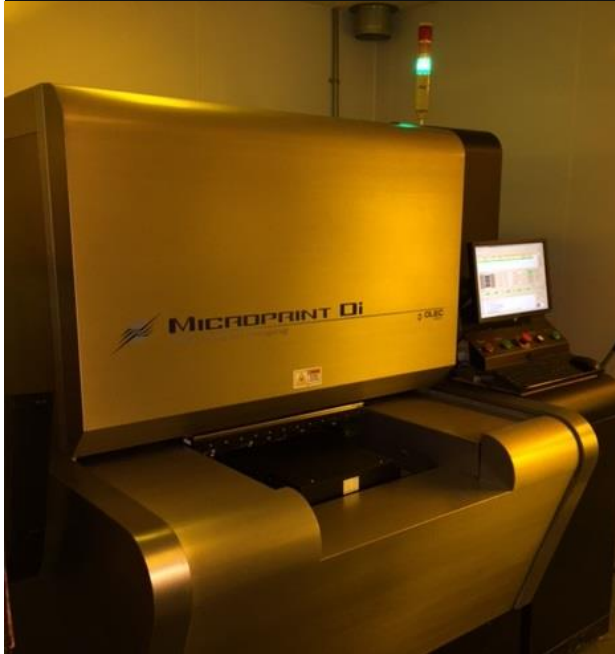


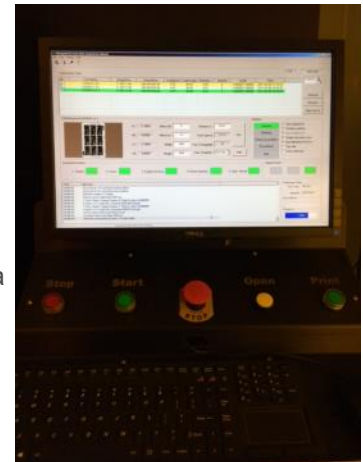
LASER DIRECT IMAGING

Fabcon Laser Direct Imaging System

January 2016



After six months of evaluation, Netvia Group has qualified Fabcon's Microprint Di, laser direct imaging system, for production use. This system bypasses the traditional process of PCB manufacturing that requires photoplots or film, in order to reproduce the circuit image onto the substrate. It also eliminates the common defects associated with film instability, nicks, cuts and deformation of the image. With the addition of the LDI, we now have the ability to expose directly onto the substrate, at a higher image resolution and with automated real time scaling on every panel produced.



From basic two layer designs with 10 mil line width and spacing, to HDI 2 mil line width & spacing, all of our clientele will benefit with the improved line width resolution, board registration and overall reliability.

Without your continued support, this would not be possible. We greatly appreciate the opportunity to do business with you.

If we can assist you in any way, please do not hesitate to let us know.

Key Features

- Elimination of artwork, with its related defects, nicks and cuts
- Exposure of line width & spacing, down to 2 mil resolution
- Improved quality of layer registration
- Quicker turn around times with elimination of artwork